

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yi-Ching WU</td> <td>06/11/2013</td> </tr> <tr> <td>Tzu-Hung YANG</td> <td>06/11/2013</td> </tr> <tr> <td>Chih-Chung WU</td> <td>06/11/2013</td> </tr> </tbody> </table>		Name	Execution Date	Yi-Ching WU	06/11/2013	Tzu-Hung YANG	06/11/2013	Chih-Chung WU	06/11/2013
Name	Execution Date								
Yi-Ching WU	06/11/2013								
Tzu-Hung YANG	06/11/2013								
Chih-Chung WU	06/11/2013								
RECEIVING PARTY DATA									
Name:	UNITED MICROELECTRONICS CORPORATION								
Street Address:	NO. 3, LI-HSIN RD. II								
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK								
City:	HSINCHU								
State/Country:	TAIWAN								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13921220</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13921220				
Property Type	Number								
Application Number:	13921220								
CORRESPONDENCE DATA									
Fax Number:	5306859794								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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NAME OF SUBMITTER:	Ding Yu Tan								
Signature:	/Ding Yu Tan/								
Date:	06/19/2013								

OP \$40.00 13921220

This document serves as an Oath/Declaration (37 CFR 1.63).

**Total Attachments: 3**

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**Declaration (37 CFR 1.63) for Utility Patent Application Using An  
Application Data Sheet (37 CFR 1.76) and  
Assignment For Single Assignee**

The title of the invention is as follow:

METHOD FOR PLANARIZING SEMICONDUCTOR DEVICES

As a below named inventor, I hereby declare that this declaration is directed to the application of which is attached hereto unless the following box is checked:

☐ was filed on \_\_\_\_\_ as United States Application Number or PCT International Application Number \_\_\_\_\_

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

WHEREAS, United Microelectronics Corporation (hereinafter referred to "Assignee") whose mailing address is NO. 3, LI-HSIN RD. II, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;

Now, therefore, in consideration of the sum of One dollars (\$ 1.00), the receipt whereof is acknowledged, and for other good and valuable consideration, I, by these presents hereby do sell, assign and transfer unto said Assignee the entire right, title, and interest in and to any and all improvements which are disclosed in said invention and, in and to, all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all continuations, continuation-in-part, divisions, renewals, substitutions, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said Assignee as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of said Assignee, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me had this Assignment and sale not been made.

Further, I agree that I will communicate to said Assignee or its (his) representatives any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said Assignee, make all rightful oaths, and, generally do everything possible to aid said Assignee, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Direct all Correspondence to:

**The Address Associated with Customer Number 66749**

Legal Name of Additional Joint Inventor, if any: Yi-Ching WU	
Inventor's signature <i>Yi-Ching Wu</i>	Date 2013.6.11

Legal Name of Additional Joint Inventor, if any: Tzu-Hung YANG	
Inventor's signature <i>Tzu-Hung Yang</i>	Date 2013.6.11

Legal Name of Additional Joint Inventor, if any: Chih-Chung WU	
Inventor's signature <i>Chih-Chung WU</i>	Date 2013.6.11

☐ Additional inventors are being named on the next page, if any